ISSOCIATION LECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
52-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information			
upplier	Information														
Company name*			Company unique ID			J	Unique ID Authority					Response Date*			
semi											2023-06-08				
ontact Na	me	Title - Contact			I	Phone - Contact*					Email - Contact*				
roduct-Eı	nv-Stewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
uthorized	Representative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
			Mfr Item Number Mfr Item Name				Effective Date	Version	on	Manufacturing Site		W	eight*	UOM	Unit Type
			SPM5 V3 INV 50	SPM5 V3 INV 500V 6.5ohm		2023-06-08			СРА		33	355.2	mg	Each	
	turing Process Informa		in-1 D	A11	CTD 020 MC	I. Dating	Davis Davis	D. d.	Tamanan	Man Tim	Dayle 7	Т	Namel	or of Dafface Cou	1
	8		Terminal Base Alloy J-STD CU Allov NA		-STD-020 MSI	L Kating	Peak Process Body Temperatur		30	ne at Peak	T		er of Reflow Cyc	cies	
	Matte Tin (Sn) - annealed		JU Alloy	I.	NA		U		IC.	30		second	s  3		
omments															
	nformation regarding materia	1	.1												

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier has provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier has not independently verified information provided by others, supplier as a minimum, its applier by the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's St										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	24.0	mg	Supplier	Silicon (Si)	7440-21-3		24	mg
Die Attach	6.0	mg	Supplier	Silver (Ag)	7440-22-4		4.56	mg
			Supplier	Phenolic Resin-2	54208-63-8		1.44	mg
Die Attach Solder	4.8	mg	Supplier	Silver (Ag)	7440-22-4		0.12	mg
			A	Lead (Pb)	7439-92-1	7a	4.44	mg
			Supplier	Tin (Sn)	7440-31-5		0.24	mg
Lead Frame	1370.0	mg	Supplier	Silver (Ag)	7440-22-4		20.002	mg
			В	Nickel (Ni)	7440-02-0		30.003	mg
			Supplier	Iron (Fe)	7439-89-6		1.37	mg
			Supplier	Copper (Cu)	7440-50-8		1318.214	mg
			Supplier	Phosphorus (P)	7723-14-0		0.411	mg
Mold Compound-Black	1890.0	mg	Supplier	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		37.8	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		274.05	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		56.7	mg
			Supplier	Carbon Black (C)	1333-86-4		9.45	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1512	mg
Plating	56.4	mg	Supplier	Tin (Sn)	7440-31-5		56.4	mg
Wire Bond - Cu	4.0	mg	Supplier	Palladium (Pd)	7440-05-3		0.08	mg
			Supplier	Copper (Cu)	7440-50-8		3.92	mg